

REMARKS

Claims 1-30 are pending in the reissue application. In the Office Action dated May 13, 2004, claims 1, 3-6, 8-9, 12-13, 15-18, 20-21, 24-31, 33-36, 38-49, 42-45 and 47-53, 54, 56, 58-59, 61-62, 65-68, and 70-76 were rejected under 35 U.S.C. §102(e) as being anticipated by Cheng et al. (U.S. 6,019,670). Claims 2, 7, 10-11, 14, 19, 22-23, 32, 37, 40-41 46, 55, 57, 60, 63-64, and 69 were rejected under 35 U.S.C. §103(a) as being unpatentable over Cheng et al. (U.S. 6,019,670) in view of Tanaka (US 5,902,173). Applicants respectfully request reconsideration of the application in view of the following remarks and amendments.

Claims 1, 6-8, 13, 18-20, and 25-30 of the original patent claims are proposed to be amended. Claims 4, 5, 10, 16-17, and 22 of the original patent claims are cancelled. Claims 31-76 have been cancelled and are proposed to be replaced with new claims 77-117.

As a preliminary matter, the Examiner has stated that the original patent or a statement as to loss or inaccessibility of the original patent must be received before this reissue application can be allowed. Applicants have submitted a copy of the date stamped post card from the USPTO evidencing receipt of the offer to surrender the original patent including the original patent. If the Examiner would like further evidence of the Applicants submission of these documents, the Applicants will provide them.

Applicants and the Examiner had an interview on July 23, 2004. Applicants and the Examiner agreed that as proposed to be amended the Cheng reference and the Tanaka reference do not disclose or fairly suggest all of the claim limitations.

With regard to claim 1, the Cheng reference and the Tanaka reference do not disclose or fairly suggest, "a first refurbishment element connected to the face of the first ring and a second refurbishment element connected to the face of the second ring, the first ring operably coupled to a first linear actuator configured to independently move the first ring downwardly to selectively engage the first refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the second ring to selectively disengage the first refurbishment element from the polishing surface and the second ring operably coupled to a second linear actuator configured to independently move the second ring downwardly to selectively engage the second refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the first ring to selectively disengage the second refurbishment element from the polishing surface, the first ring being positioned radially outward

from the perimeter of the wafer carrier and the second ring being positioned radially outward from the first ring, the first and the second refurbishing elements being adapted to engage the polishing surface substantially adjacent to the perimeter portion of the wafer carrier.” Claims depending from claim 1 are also allowable due to depending from an allowable base claim and further in view of the additional limitations recited in the dependent claims.

With regard to claim 13, the Cheng reference and the Tanaka reference do not disclose or fairly suggest, “a pad refurbisher having a body including a first ring and a second ring each with a face positioned proximate to a perimeter portion of the wafer carrier and facing generally towards the polishing surface, the first ring having a first refurbishment element connected to the face thereof, the first ring operably coupled to a first linear actuator configured to independently move the first ring downwardly to selectively engage the first refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the second ring to selectively disengage the first refurbishment element from the polishing surface and the second ring having a second refurbishment element connected to the face thereof, the second ring operably coupled to a second linear actuator configured to independently move the second ring downwardly to selectively engage the second refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the first ring to selectively disengage the second refurbishment element from the polishing surface, the first ring being positioned radially outward from the perimeter of the wafer carrier and the second ring being positioned radially outward from the first ring, the body being attached to the wafer carrier so that the body and the first and the second refurbishing elements travel with the wafer carrier as the wafer carrier moves with respect to the polishing pad, wherein the first refurbishing element engages the polishing surface substantially adjacent to the perimeter portion of the wafer carrier while the wafer carrier moves the wafer over the polishing surface.” Claims depending from claim 13 are also allowable due to depending from an allowable base claim and further in view of the additional limitations recited in the dependent claims.

With regard to claim 25, the Cheng reference and the Tanaka reference do not disclose or fairly suggest, “selectively engaging one of the first and the second refurbishing elements with the polishing pad.” Claims depending from claim 25 are also allowable due to depending from an allowable base claim and further in view of the additional limitations recited in the dependent claims.

With regard to claim 77, the Cheng reference and the Tanaka reference do not disclose or fairly suggest, “a first refurbishment element connected to the face of the first ring and a second refurbishment element connected to the face of the second ring, the first ring operably coupled to a first linear actuator configured to independently move the first ring downwardly to selectively engage the first refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the second ring to selectively disengage the first refurbishment element from the polishing surface and the second ring operably coupled to a second linear actuator configured to independently move the second ring downwardly to selectively engage the second refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the first ring to selectively disengage the second refurbishment element from the polishing surface, the first ring being positioned radially outward from the perimeter of the wafer carrier and the second ring being positioned radially outward from the first ring, the first and the second refurbishing elements being adapted to engage the polishing surface substantially adjacent to the perimeter portion of the wafer carrier.” Claims depending from claim 77 are also allowable due to depending from an allowable base claim and further in view of the additional limitations recited in the dependent claims.

With regard to claim 88, the Cheng reference and the Tanaka reference do not disclose or fairly suggest, “a pad refurbisher having a body attached to the wafer carrier, the body including a first ring having a first refurbishment element and a second ring having a second refurbishment element, the first ring operably coupled to a first linear actuator configured to independently move the first ring downwardly to selectively engage the first refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the second ring to selectively disengage the first refurbishment element from the polishing surface and the second ring operably coupled to a second linear actuator configured to independently move the second ring downwardly to selectively engage the second refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the first ring to selectively disengage the second refurbishment element from the polishing surface, the first ring being positioned radially outward from the perimeter of the wafer carrier and the second ring being positioned radially outward from the first ring.” Claims depending from claim 88 are also allowable due to depending from an allowable base claim and further in view of the additional limitations recited in the dependent claims.

With regard to claim 92, , the Cheng reference and the Tanaka reference do not disclose or fairly suggest, “selectively engaging one of the first and the second refurbishing elements with the polishing pad.” Claims depending from claim 92 are also allowable due to depending from an allowable base claim and further in view of the additional limitations recited in the dependent claims.

With regard to claim 99, the Cheng reference and the Tanaka reference do not disclose or fairly suggest, “a first refurbishment element connected to the face of the first ring and a second refurbishment element connected to the face of the second ring, the first ring operably coupled to a first linear actuator configured to independently move the first ring downwardly to selectively engage the first refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the second ring to selectively disengage the first refurbishment element from the polishing surface and the second ring operably coupled to a second linear actuator configured to independently move the second ring downwardly to selectively engage the second refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the first ring to selectively disengage the second refurbishment element from the polishing surface, the first ring being positioned radially outward from the perimeter of the wafer carrier and the second ring being positioned radially outward from the first ring, the first and the second refurbishing elements being adapted to engage the polishing surface substantially adjacent to the perimeter portion of the wafer carrier.” Claims depending from claim 99 are also allowable due to depending from an allowable base claim and further in view of the additional limitations recited in the dependent claims.

With regard to claim 108, the Cheng reference and the Tanaka reference do not disclose or fairly suggest, “a pad refurbisher having a body including a first ring bearing a first refurbishment element and a second ring bearing a second refurbishment element, the body being movably attached to the wafer carrier, the first ring operably coupled to a first linear actuator configured to independently move the first ring downwardly to selectively engage the first refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and second ring to selectively disengage the first refurbishment element from the polishing surface and the second ring operably coupled to a second linear actuator configured to independently move the second ring downwardly to selectively engage the second refurbishment element with the polishing surface and upwardly with respect to the wafer carrier and the first

ring to selectively disengage the second refurbishment element from the polishing surface, the first ring being positioned radially outward from the perimeter of the wafer carrier and the second ring being positioned radially outward from the first ring.” Claims depending from claim 108 are also allowable due to depending from an allowable base claim and further in view of the additional limitations recited in the dependent claims.

With regard to claim 112, the Cheng reference and the Tanaka reference do not disclose or fairly suggest, “selectively engaging one of the first and the second refurbishing elements with the polishing pad.” Claims depending from claim 112 are also allowable due to depending from an allowable base claim and further in view of the additional limitations recited in the dependent claims.

All of the claims remaining in the application are now clearly allowable. Favorable consideration and a Notice of Allowance are earnestly solicited.

Respectfully submitted,
DORSEY & WHITNEY LLP



Marcus Simon
Registration No. 50,258
Telephone No. (206) 903-8787

MSS:clr

Enclosures:

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Check
Fee Transmittal Sheet (+ copy)
Copy of date-stamped postcard

DORSEY & WHITNEY LLP
1420 Fifth Avenue, Suite 3400
Seattle, Washington 98101-4010
(206) 903-8800 (telephone)
(206) 903-8820 (fax)



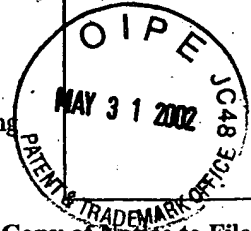
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DORSEY & WHITNEY LLP